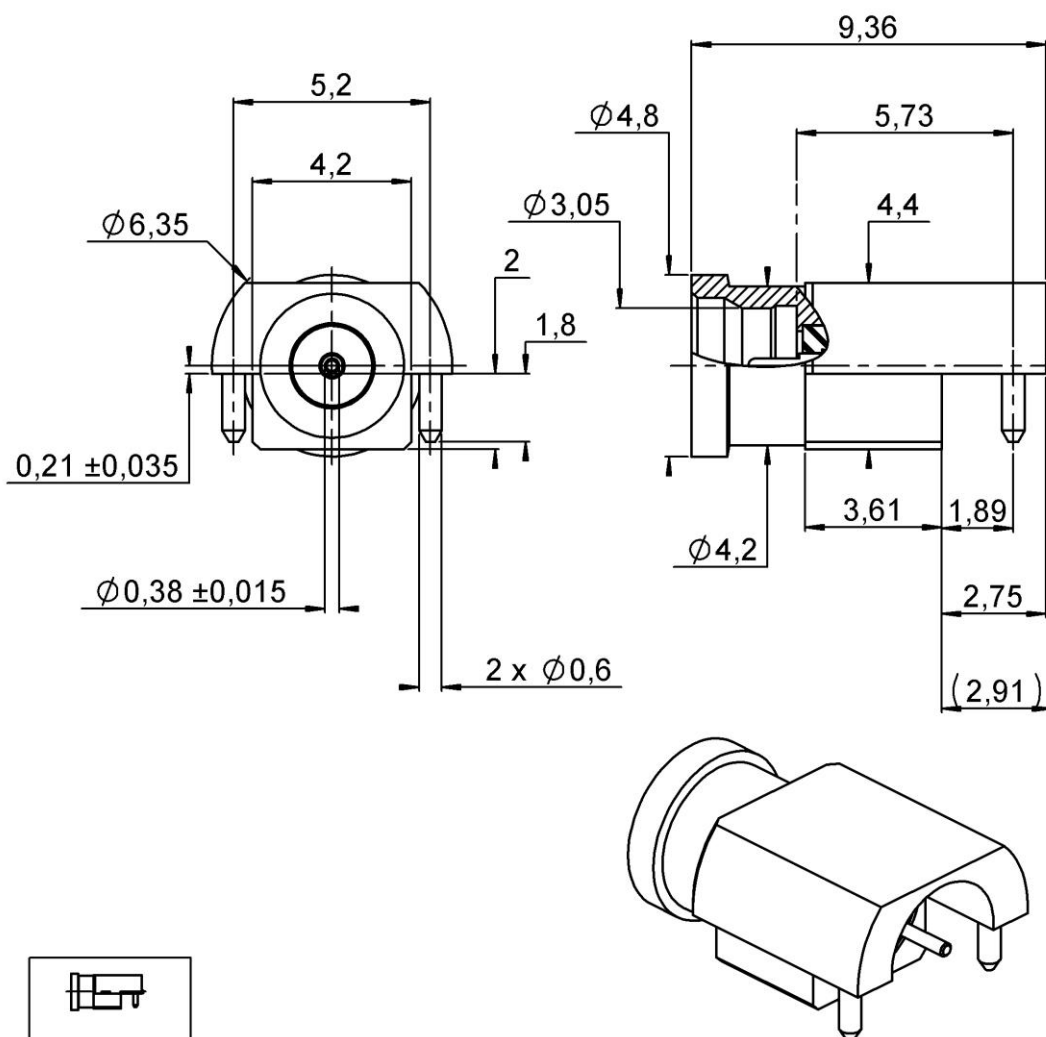


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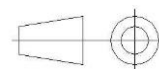
SERIES **SMP LOCK**

PART NUMBER **R222L00030**



Scale: 1/1

All dimensions are in mm. Tolerances according ISO 2768 m-H



| COMPONENTS | MATERIALS | PLATING (µm) |
|----------------|-------------------------|--------------------------|
| Body | STAINLESS STEEL | GOLD OVER NICKEL. |
| Center contact | BERYLLIUM COPPER | GOLD OVER NICKEL. |
| Outer contact | | |
| Insulator | PTFE | |
| Gasket | | |
| Others parts | | |
| - | - | - |
| - | - | - |

| | | | |
|----------|---------------------------|------------------------|-------------------------------|
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|----------|---------------------------|------------------------|-------------------------------|

PACKAGING

| Standard | Unit | Other |
|------------|-------------------|-------------------|
| 100 | Contact us | Contact us |

ELECTRICAL CHARACTERISTICS

| | | |
|---------------------------------|--------------------|--------------------------|
| Impedance | 50 | Ω |
| Frequency | 0-18 | GHz |
| VSWR | *1.5 + 0,00 | x F(GHz) Maxi |
| Insertion loss | 0.18 | \sqrt{F} (GHz) dB Maxi |
| RF leakage | - (NA | - F(GHz)) dB Maxi |
| Voltage rating | 335 | Veff Maxi |
| Dielectric withstanding voltage | 500 | Veff mini |
| Insulation resistance | 5000 | M Ω mini |

MECHANICAL CHARACTERISTICS

| | | |
|----------------------------|------------|-----------|
| Center contact retention | | |
| Axial force – Mating End | 6.8 | N mini |
| Axial force – Opposite end | 6.8 | N mini |
| Torque | NA | N.cm mini |

| | | |
|--------------------|-----------|------|
| Recommended torque | | |
| Mating | NA | N.cm |
| Panel nut | NA | N.cm |

| | | |
|---------------------------|-------------|-------------|
| Mating life | 500 | Cycles mini |
| Nominal Weight | 0,91 | g |
| (Add +15% for max weight) | | |

ENVIRONMENTAL

| | | |
|-----------------------|-----------------|-----------|
| Operating temperature | -65/+165 | °C |
| Hermetic seal | NA | Atm.cm3/s |
| Panel leakage | NA | |

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:

Others:

***At 12.4GHz - Performance strongly depends on layout and PCB material**

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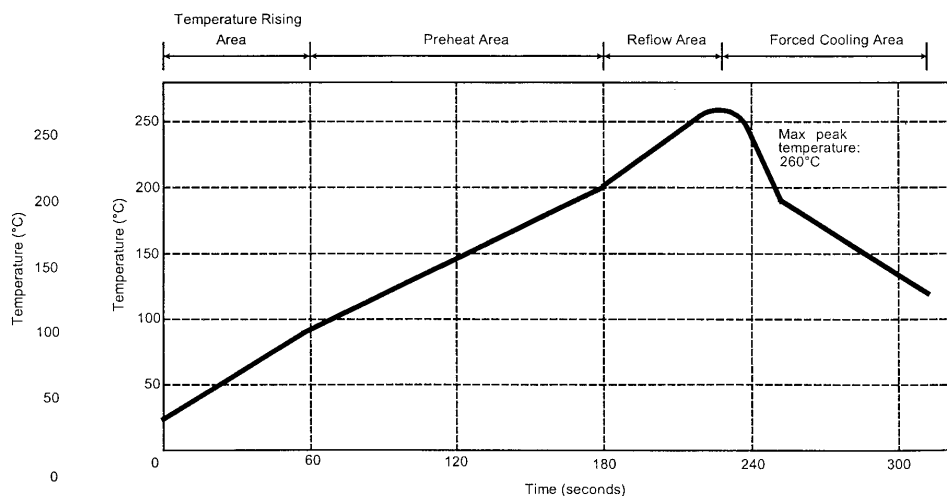
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SOLDER PROCEDURE

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application.
We recommend a low residue flux.
We advise a thickness of 150 microns (.5.9 micro inch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
3. Soldering by infra-red reflow.
Below, please find the typical profile to use.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.



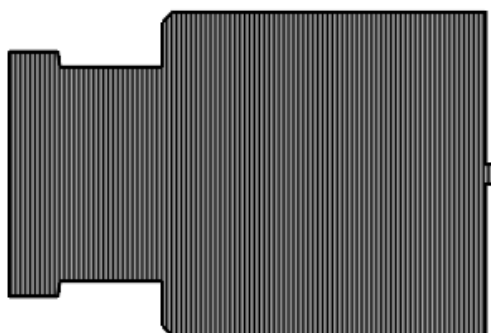
| Parameter | Value | Unit |
|----------------------------------|-----------|--------|
| Temperature rising Area | 1 - 4 | °C/sec |
| Max Peak Temperature | 260 | °C |
| Max dwell time @260°C | 10 | sec |
| Min dwell time @235°C | 20 | sec |
| Max dwell time @235°C | 60 | sec |
| Temperature drop in cooling Area | -1 to - 4 | °C/sec |
| Max dwell time above 100°C | 420 | sec |

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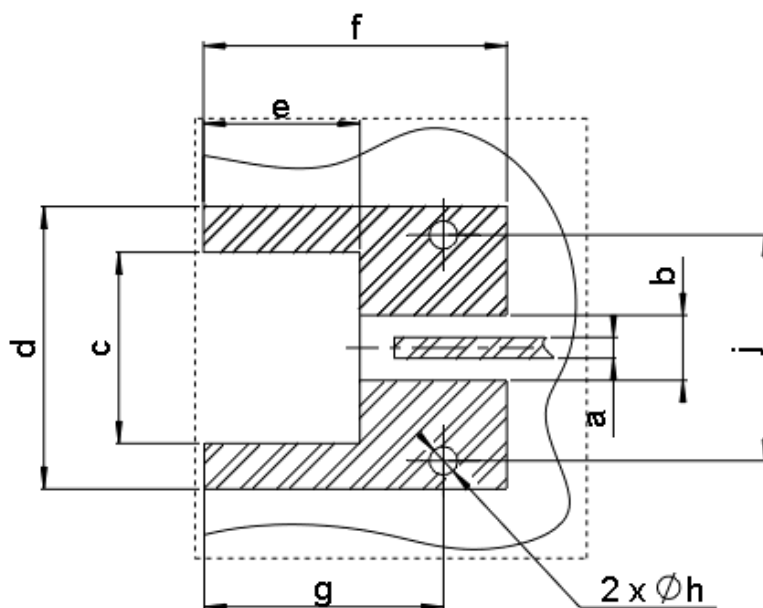
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Shadow of receptacle
for video camera



| | |
|---|-------------|
| a | 0,48 |
| b | 1,5 |
| c | 4,28 - 4,42 |
| d | 6,5 |
| e | 3,5 - 3,7 |
| f | 6,98 |
| g | 5,5 |
| h | 0,65 |
| j | 5,2 |